

iMAPS New England – 45th Symposium & Expo

**The Largest Regional Symposium Dedicated to
Microelectronics, Assembly and Packaging**

Boxboro Regency Hotel & Conference Center

Boxborough, Massachusetts

May 1, 2018



EarlyBird Exhibitor Registration is Open!!

The Technical Program is Being Assembled

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The New England Chapter

Call for Papers & Posters

- 2D-3D & Beyond
- Medical Device Packaging
- RF & Microwave Innovative Technologies
- Wire & Die Bonding, Flip Chip, Bumping, TSV
- SMT & Electronics Assembly-Packaging
- Thermal Management Materials & Designs
- Military, Defense & Space Microelectronics
- High Temperature Electronics
- MEMS Sensors & Nano Technology
- Wearables - Consumer Applications
- Advanced Semiconductor Packaging
- Printed Electronics - Additive Manufacturing
- Nanoelectronic - Optoelectronic Packaging
- New & Emerging Materials-Technologies

Please e-mail your 250 word abstract to:

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Deadline for Submission – December 31, 2017

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